

Tpli 200 Series Thermal Gap Filler

*Ready for 5G

PRODUCT DESCRIPTION

Tpli[™] 200 is a premium gap filler. A unique blend of boron nitride and silicone produce the highest performing interface pad.

Tpli 200's exceptional combination of high thermal conductivity and compliancy generate unmatched thermal resistances in a gap filling interface material.

Tpli 200 absorbs shock and relieves stresses, thus minimizing potential damage to components. Tpli 200 is electrically insulating, stable from -45°C to 200°C, and meets UL 94 HB rating.

FEATURES AND BENEFITS

- Soft and compliant
- High Thermal performance
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	TYPICAL VALUE	TEST METHOD
Construction & Composition	Boron nitride filled silicone sheet	N/A
Color	Varies by thickness	Visual
Thickness Range	0.25mm (0.010") - 5.08mm (0.20")	N/A
Thickness Tolerance	+/- 10%	N/A
Thermal Conductivity (W/mK)	6.0	ASTM D5470
Density (g/cc)	1.4	Helium
		Pyncometer
Hardness (Shore 00)	70	ASTM D2240
Outgassing TML (weight %)	0.46	ASTM E595
Outgassing CVCM (weight %)	0.15	ASTM E595
Temperature Range	-45°C to 200°C	N/A
Rth@ 40 mils, 10 psi, 50⁰C	0.25°C–in2/W	ASTM D5470
		(modified)
* Dielectric Constant @ 10GHz	3.2 *	ASTM D150
UL Flammability Rating	НВ	UL 94
Volume Resistivity	5x10^13 ohm-cm	ASTM D257

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AVAILABILITY

STANDARD THICKNESSES

- 0.25mm (0.010") to 5.0mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 16" x 16" and 8" x 8" or custom die cut parts

REINFORCEMENT

- Fiberglass is required in thicknesses of 0.010" (0.25mm) and 0.015" (0.38mm)
- Reinforcement is optional in thicknesses 0.020" (0.5mm) and 0.025" (0.63mm). Indicate fiberglass by "FG" suffix
- Thicknesses above 0.025" (0.063mm) are not reinforced

OPTIONS

- A0 no adhesive
- A1 adhesive on one side

POST CURE

• Post Curing option available. Indicate post cure by "PC" suffix

PART NUMBER SYSTEM

Tflex[™] indicates Laird elastomeric thermal gap filler product line. Tpli 2xx indicates Tpli 200 product line with thickness in mils (0.001")

EXAMPLES:

- Tpli 240,A0 = 0.040 inch thick Tpli[™] 200 material with no adhesive
- Tpli 280,A1 = 0.080 inch thick Tpli[™] 200 material with one side adhesive
- Tpli 220FG,A1 = 0.020 inch thick Tpli[™] 200 material with fiberglass reinforcement and one side adhesive
- Tpli 260,PC = 0.060 inch thick Tpli[™] 200 material post cured

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